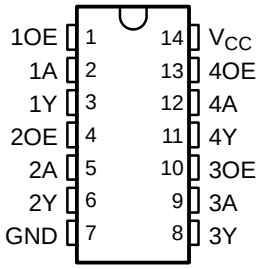
# SN74LVC126A
# QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCAS339Q – MARCH 1994 – REVISED JULY 2005

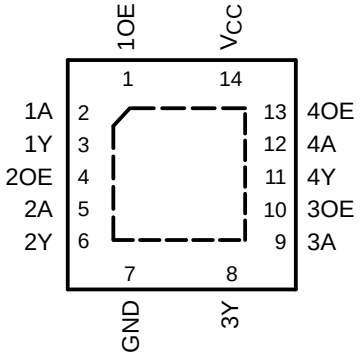
## FEATURES

- **Operates From 1.65 V to 3.6 V**
- **Specified From –40°C to 85°C and From –40°C to 125°C**
- **Inputs Accept Voltages to 5.5 V**
- **Max $t_{pd}$ of 4.7 ns at 3.3 V**
- **Typical $V_{OLP}$ (Output Ground Bounce) < 0.8 V at $V_{CC}$ = 3.3 V, $T_A$ = 25°C**
- **Typical $V_{OHV}$ (Output $V_{OH}$ Undershoot) > 2 V at $V_{CC}$ = 3.3 V, $T_A$ = 25°C**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**

**D, DB, DGV, NS, OR PW PACKAGE**
**(TOP VIEW)**




**RGY PACKAGE**
**(TOP VIEW)**




## DESCRIPTION/ORDERING INFORMATION

This quadruple bus buffer gate is designed for 1.65-V to 3.6-V $V_{CC}$ operation.

The SN74LVC126A features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is low.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

**ORDERING INFORMATION**

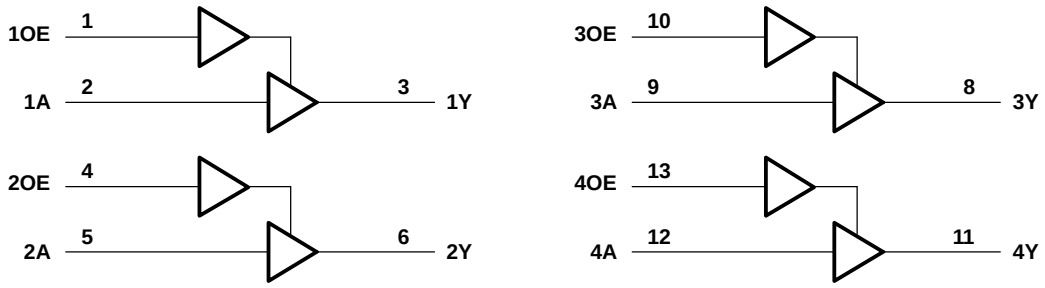
| $T_A$ | PACKAGE(1) | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---|---|---|---|---|
| –40°C to 85°C | QFN – RGY | Reel of 1000 | SN74LVC126ARGYR | LC126A |
| –40°C to 125°C | SOIC – D | Tube of 50 | SN74LVC126AD | LVC126A |
| | | Reel of 2500 | SN74LVC126ADR | |
| | | Reel of 250 | SN74LVC126ADT | |
| | SOP – NS | Reel of 2000 | SN74LVC126ANSR | LVC126A |
| | SSOP – DB | Reel of 2000 | SN74LVC126ADBR | LC126A |
| | TSSOP – PW | Tube of 90 | SN74LVC126APW | LC126A |
| | | Reel of 2000 | SN74LVC126APWR | |
| | | Reel of 250 | SN74LVC126APWT | |
| | TVSOP – DGV | Reel of 2000 | SN74LVC126ADGVR | LC126A |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**FUNCTION TABLE (EACH BUFFER)**

| INPUTS | | OUTPUT Y |
|---|---|---|
| OE | A | |
| H | H | H |
| H | L | L |
| L | X | Z |

**LOGIC DIAGRAM (POSITIVE LOGIC)**




## Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage range | | –0.5 | 6.5 | V |
| $V_I$ | Input voltage range(2) | | –0.5 | 6.5 | V |
| $V_O$ | Output voltage range(2)(3) | | –0.5 | $V_{CC}$ + 0.5 | V |
| $I_{IK}$ | Input clamp current | $V_I$ < 0 | | –50 | mA |
| $I_{OK}$ | Output clamp current | $V_O$ < 0 | | –50 | mA |
| $I_O$ | Continuous output current | | | ±50 | mA |
| | Continuous current through $V_{CC}$ or GND | | | ±100 | mA |
| $\theta_{JA}$ | Package thermal impedance | D package(4) | | 86 | °C/W |
| | | DB package(4) | | 96 | |
| | | DGV package(4) | | 127 | |
| | | NS package(4) | | 76 | |
| | | PW package(4) | | 113 | |
| | | RGY package(5) | | 47 | |
| $T_{stg}$ | Storage temperature range | | –65 | 150 | °C |
| $P_{tot}$ | Power dissipation | $T_A$ = –40°C to 125°C(6)(7) | | 500 | mW |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The value of $V_{CC}$ is provided in the recommended operating conditions table.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.
(5) The package thermal impedance is calculated in accordance with JESD 51-5.
(6) For the D package: above 70°C, the value of $P_{tot}$ derates linearly with 8 mW/K.
(7) For the DB, NS, and PW packages: above 60°C, the value of $P_{tot}$ derates linearly with 5.5 mW/K.

## Recommended Operating Conditions(1)

| | | | $T_A$ = 25°C | | –40 TO 85°C | | –40 TO 125°C | | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| $V_{CC}$ | Supply voltage | Operating | 1.65 | 3.6 | 1.65 | 3.6 | 1.65 | 3.6 | V |
| | | Data retention only | 1.5 | | 1.5 | | 1.5 | | |
| $V_{IH}$ | High-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | 0.65 × $V_{CC}$ | | 0.65 × $V_{CC}$ | | 0.65 × $V_{CC}$ | | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | 1.7 | | 1.7 | | 1.7 | | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | 2 | | 2 | | 2 | | |
| $V_{IL}$ | Low-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | | 0.35 × $V_{CC}$ | | 0.35 × $V_{CC}$ | | 0.35 × $V_{CC}$ | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | | 0.7 | | 0.7 | | 0.7 | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | | 0.8 | | 0.8 | | 0.8 | |
| $V_I$ | Input voltage | | 0 | 5.5 | 0 | 5.5 | 0 | 5.5 | V |
| $V_O$ | Output voltage | | 0 | $V_{CC}$ | 0 | $V_{CC}$ | 0 | $V_{CC}$ | V |
| $I_{OH}$ | High-level output current | $V_{CC}$ = 1.65 V | | –4 | | –4 | | –4 | mA |
| | | $V_{CC}$ = 2.3 V | | –8 | | –8 | | –8 | |
| | | $V_{CC}$ = 2.7 V | | –12 | | –12 | | –12 | |
| | | $V_{CC}$ = 3 V | | –24 | | –24 | | –24 | |
| $I_{OL}$ | Low-level output current | $V_{CC}$ = 1.65 V | | 4 | | 4 | | 4 | mA |
| | | $V_{CC}$ = 2.3 V | | 8 | | 8 | | 8 | |
| | | $V_{CC}$ = 2.7 V | | 12 | | 12 | | 12 | |
| | | $V_{CC}$ = 3 V | | 24 | | 24 | | 24 | |
| Δt/Δv | Input transition rise or fall rate | | | 10 | | 10 | | 10 | ns/V |

(1) All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | $V_{CC}$ | $T_A$ = 25°C | | | –40 TO 85°C | | –40 TO 125°C | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| $V_{OH}$ | $I_{OH}$ = –100 μA | 1.65 V to 3.6 V | $V_{CC}$ – 0.2 | | | $V_{CC}$ – 0.2 | | $V_{CC}$ – 0.3 | | V |
| | $I_{OH}$ = –4 mA | 1.65 V | 1.29 | | | 1.2 | | 1.05 | | |
| | $I_{OH}$ = –8 mA | 2.3 V | 1.9 | | | 1.7 | | 1.55 | | |
| | $I_{OH}$ = –12 mA | 2.7 V | 2.2 | | | 2.2 | | 2.05 | | |
| | | 3 V | 2.4 | | | 2.4 | | 2.25 | | |
| | $I_{OH}$ = –24 mA | 3 V | 2.3 | | | 2.2 | | 2 | | |
| $V_{OL}$ | $I_{OL}$ = 100 μA | 1.65 V to 3.6 V | | | 0.1 | | 0.2 | | 0.3 | V |
| | $I_{OL}$ = 4 mA | 1.65 V | | | 0.24 | | 0.45 | | 0.6 | |
| | $I_{OL}$ = 8 mA | 2.3 V | | | 0.3 | | 0.7 | | 0.75 | |
| | $I_{OL}$ = 12 mA | 2.7 V | | | 0.4 | | 0.4 | | 0.6 | |
| | $I_{OL}$ = 24 mA | 3 V | | | 0.55 | | 0.55 | | 0.8 | |
| $I_I$ | $V_I$ = 5.5 V or GND | 3.6 V | | | ±1 | | ±5 | | ±20 | μA |
| $I_{OZ}$ | $V_O$ = $V_{CC}$ or GND | 3.6 V | | | ±1 | | ±10 | | ±20 | μA |
| $I_{CC}$ | $V_I$ = $V_{CC}$ or GND, $I_O$ = 0 | 3.6 V | | | 1 | | 10 | | 40 | μA |
| $\Delta I_{CC}$ | One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND | 2.7 V to 3.6 V | | | 500 | | 500 | | 5000 | μA |
| $C_i$ | $V_I$ = $V_{CC}$ or GND | 3.3 V | | 4.5 | | | | | | pF |
| $C_o$ | $V_O$ = $V_{CC}$ or GND | 3.3 V | | 7 | | | | | | pF |

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

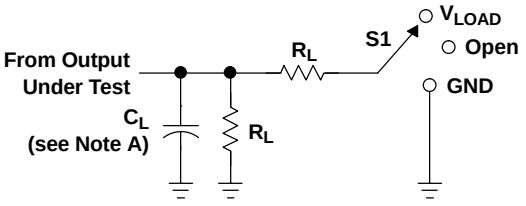
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ | $T_A$ = 25°C | | | –40 TO 85°C | | –40 TO 125°C | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| $t_{pd}$ | A | Y | 1.8 V ± 0.15 V | 1 | 4.2 | 9.3 | 1 | 9.8 | 1 | 11.3 | ns |
| | | | 2.5 V ± 0.2 V | 1 | 2.7 | 6.7 | 1 | 7.2 | 1 | 9.3 | |
| | | | 2.7 V | 1 | 2.9 | 5 | 1 | 5.2 | 1 | 6.5 | |
| | | | 3.3 V ± 0.3 V | 1 | 2.5 | 4.5 | 1 | 4.7 | 1 | 6 | |
| $t_{en}$ | OE | Y | 1.8 V ± 0.15 V | 1 | 4.8 | 9.5 | 1 | 10 | 1 | 11.5 | ns |
| | | | 2.5 V ± 0.2 V | 1 | 2.8 | 7.8 | 1 | 8.3 | 1 | 10.4 | |
| | | | 2.7 V | 1 | 3.1 | 6.1 | 1 | 6.3 | 1 | 8 | |
| | | | 3.3 V ± 0.3 V | 1 | 2.5 | 5.5 | 1 | 5.7 | 1 | 7.5 | |
| $t_{dis}$ | OE | Y | 1.8 V ± 0.15 V | 1 | 4.4 | 12.1 | 1 | 12.6 | 1 | 14.1 | ns |
| | | | 2.5 V ± 0.2 V | 1 | 2.7 | 8.2 | 1 | 8.7 | 1 | 10.8 | |
| | | | 2.7 V | 1 | 2.7 | 6.5 | 1 | 6.7 | 1 | 8.5 | |
| | | | 3.3 V ± 0.3 V | 1.3 | 2.3 | 5.8 | 1.3 | 6 | 1.3 | 7.5 | |
| $t_{sk(o)}$ | | | 3.3 V ± 0.3 V | | | | | 1 | | 1.5 | ns |

## Operating Characteristics

$T_A$ = 25°C

| PARAMETER | | TEST CONDITIONS | $V_{CC}$ | TYP | UNIT |
|---|---|---|---|---|---|
| $C_{pd}$ Power dissipation capacitance per gate | Outputs enabled | f = 10 MHz | 1.8 V | 20 | pF |
| | | | 2.5 V | 21 | |
| | | | 3.3 V | 22 | |
| | Outputs disabled | | 1.8 V | 2 | |
| | | | 2.5 V | 3 | |
| | | | 3.3 V | 4 | |

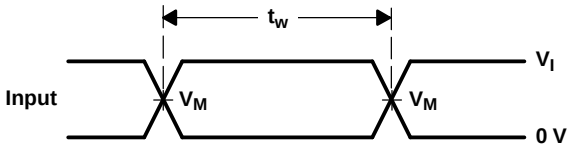
## PARAMETER MEASUREMENT INFORMATION



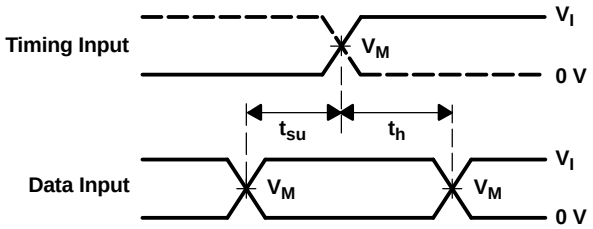

LOAD CIRCUIT

| TEST | S1 |
|---|---|
| $t_{PLH}/t_{PHL}$ | Open |
| $t_{PLZ}/t_{PZL}$ | $V_{LOAD}$ |
| $t_{PHZ}/t_{PZH}$ | GND |

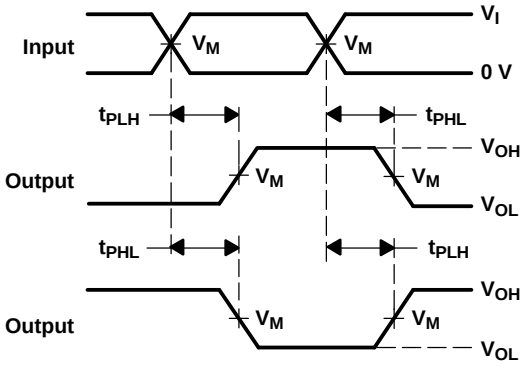
| $V_{CC}$ | INPUTS | | $V_M$ | $V_{LOAD}$ | $C_L$ | $R_L$ | $V_\Delta$ |
|---|---|---|---|---|---|---|---|
| | $V_I$ | $t_r/t_f$ | | | | | |
| 1.8 V ± 0.15 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 kΩ | 0.15 V |
| 2.5 V ± 0.2 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| 2.7 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| 3.3 V ± 0.3 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |



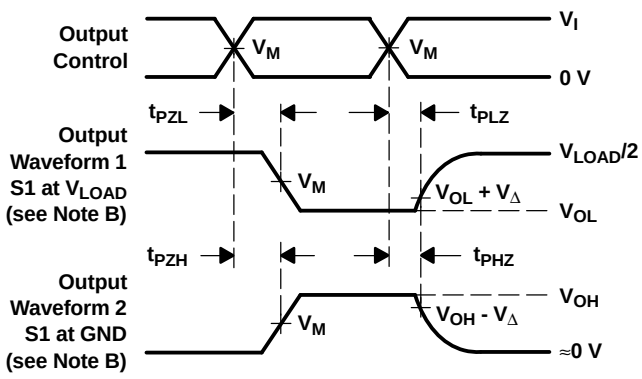

VOLTAGE WAVEFORMS
PULSE DURATION




VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O$ = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. $t_{PLZ}$ and $t_{PHZ}$ are the same as $t_{dis}$.
F. $t_{PZL}$ and $t_{PZH}$ are the same as $t_{en}$.
G. $t_{PLH}$ and $t_{PHL}$ are the same as $t_{pd}$.
H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LVC126AD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADBLE | OBSOLETE | SSOP | DB | 14 | | TBD | Call TI | Call TI | -40 to 125 | | |
| SN74LVC126ADBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126ADE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADGVR | ACTIVE | TVSOP | DGV | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126ADGVRE4 | ACTIVE | TVSOP | DGV | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126ADR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ADTG4 | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126ANSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC126A | Samples |
| SN74LVC126APW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126APWG4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126APWLE | OBSOLETE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -40 to 125 | | |
| SN74LVC126APWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126APWRE4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LVC126APWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126APWT | ACTIVE | TSSOP | PW | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC126A | Samples |
| SN74LVC126ARGYR | ACTIVE | VQFN | RGY | 14 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | LC126A | Samples |
| SN74LVC126ARGYRG4 | ACTIVE | VQFN | RGY | 14 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | LC126A | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74LVC126A :**

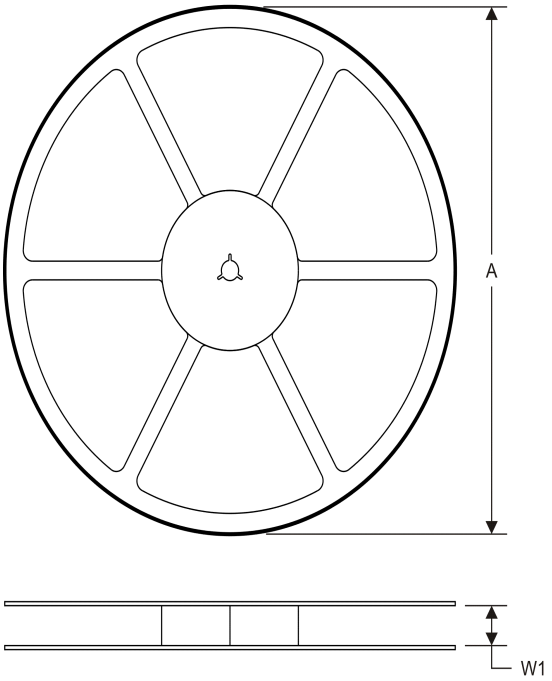
- Automotive: SN74LVC126A-Q1

NOTE: Qualified Version Definitions:

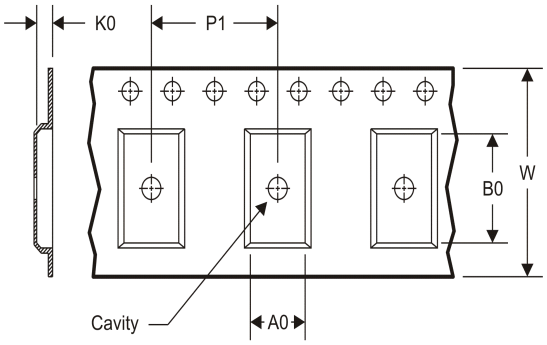
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS




### TAPE DIMENSIONS



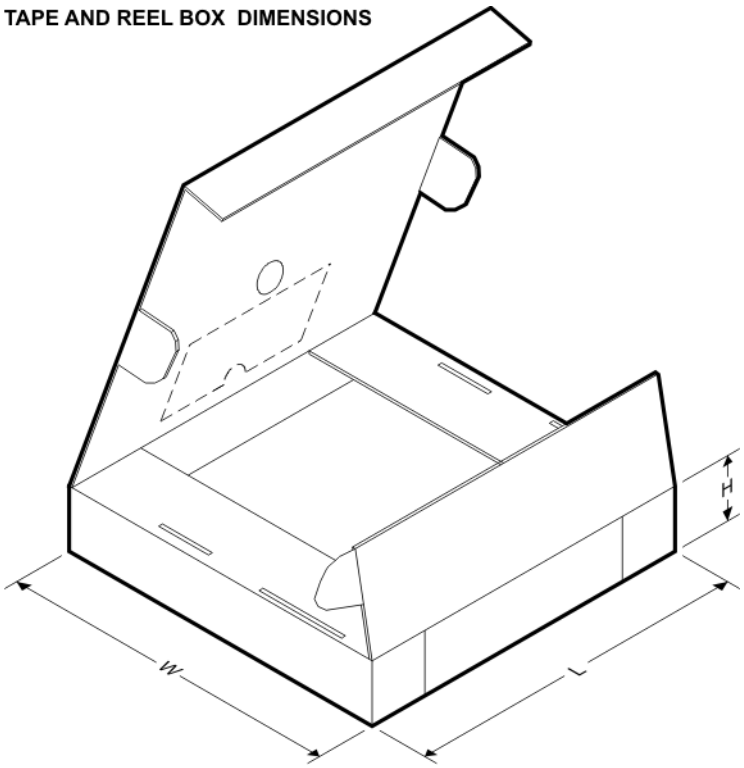

| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

### TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LVC126ADBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVC126ADGVR | TVSOP | DGV | 14 | 2000 | 330.0 | 12.4 | 6.8 | 4.0 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC126ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC126ADT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC126ANSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVC126APWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC126APWT | TSSOP | PW | 14 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC126ARGYR | VQFN | RGY | 14 | 3000 | 330.0 | 12.4 | 3.75 | 3.75 | 1.15 | 8.0 | 12.0 | Q1 |

**TAPE AND REEL BOX DIMENSIONS**

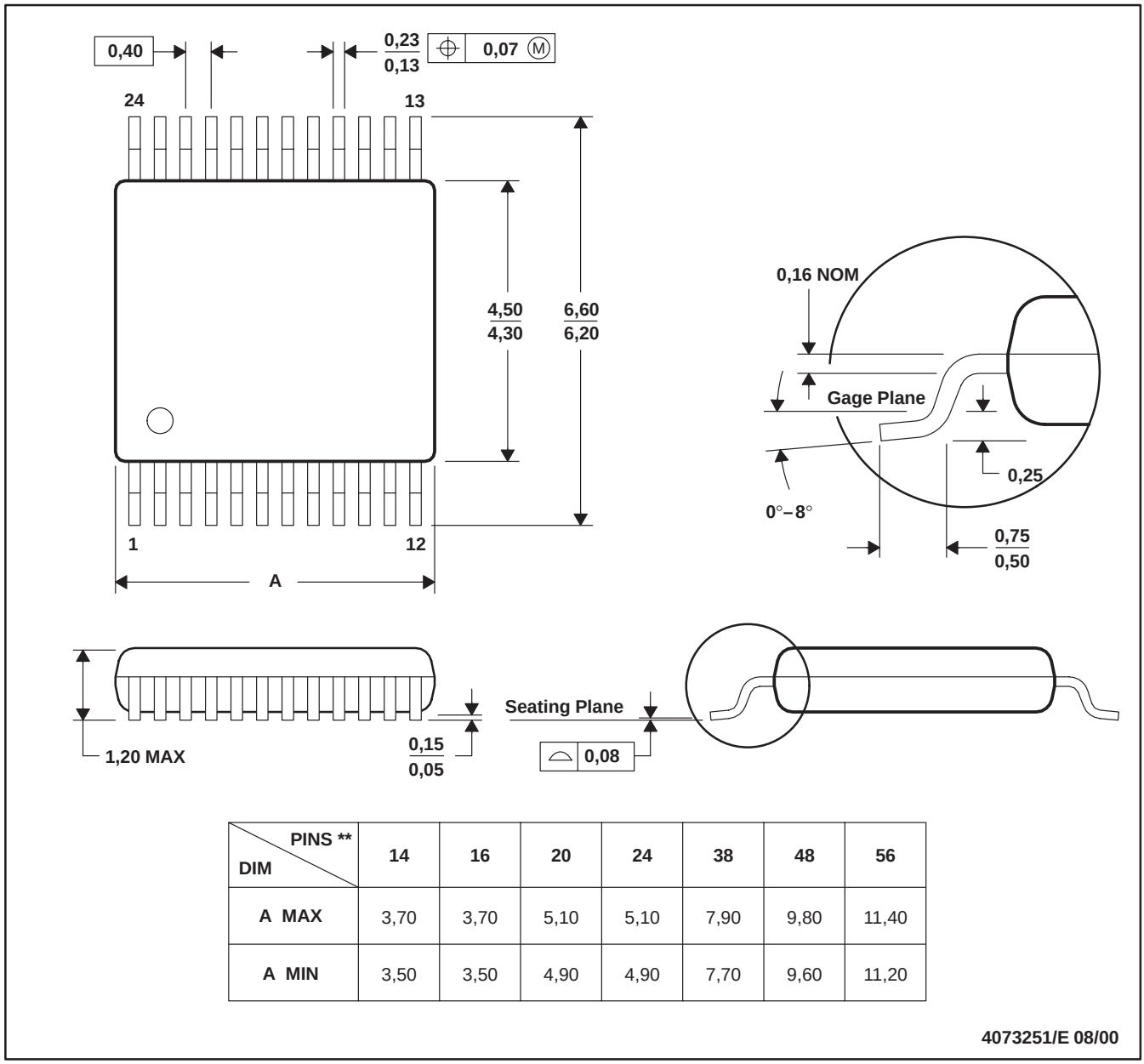



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74LVC126ADBR | SSOP | DB | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LVC126ADGVR | TVSOP | DGV | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74LVC126ADR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74LVC126ADT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| SN74LVC126ANSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LVC126APWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74LVC126APWT | TSSOP | PW | 14 | 250 | 367.0 | 367.0 | 35.0 |
| SN74LVC126ARGYR | VQFN | RGY | 14 | 3000 | 367.0 | 367.0 | 35.0 |

**DGV (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE**

**24 PINS SHOWN**

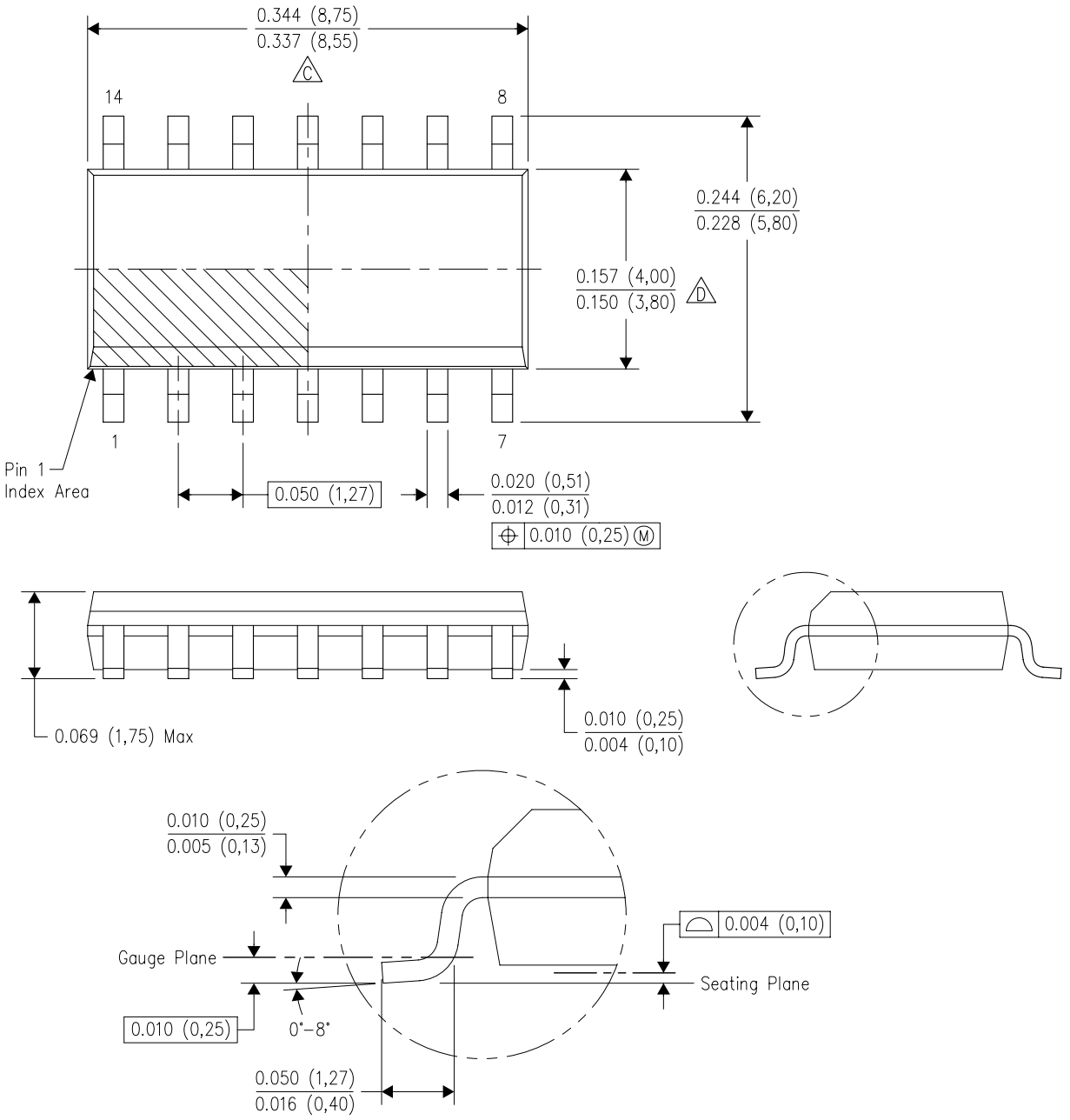



| DIM \ PINS ** | 14 | 16 | 20 | 24 | 38 | 48 | 56 |
|---|---|---|---|---|---|---|---|
| A MAX | 3,70 | 3,70 | 5,10 | 5,10 | 7,90 | 9,80 | 11,40 |
| A MIN | 3,50 | 3,50 | 4,90 | 4,90 | 7,70 | 9,60 | 11,20 |

**4073251/E 08/00**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

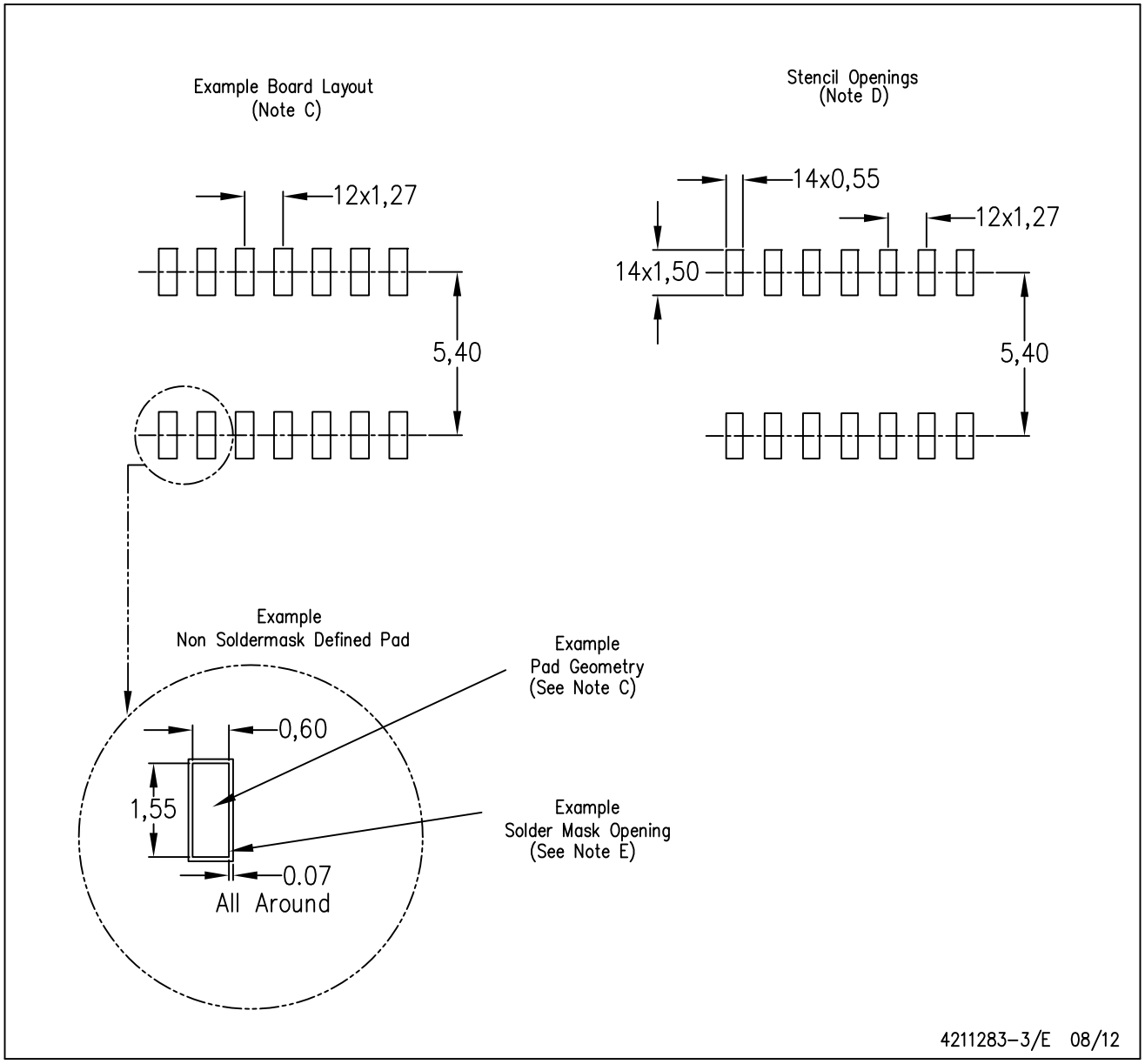
D (R–PDSO–G14) PLASTIC SMALL OUTLINE




4040047–5/M 06/11

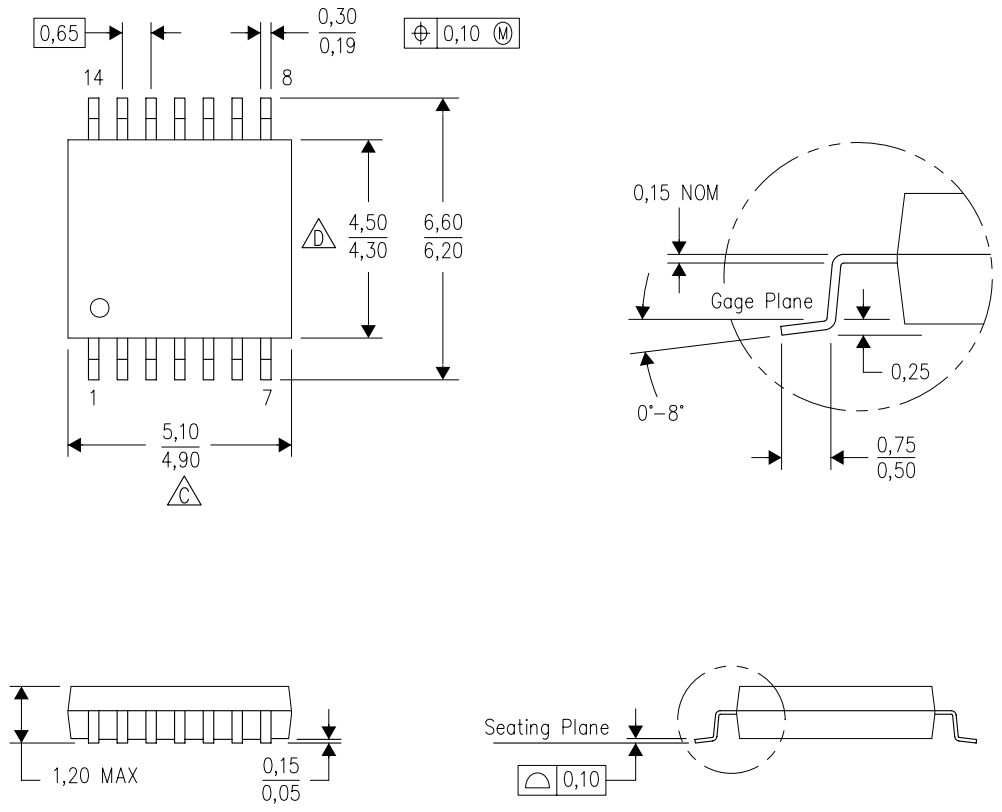
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE




NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

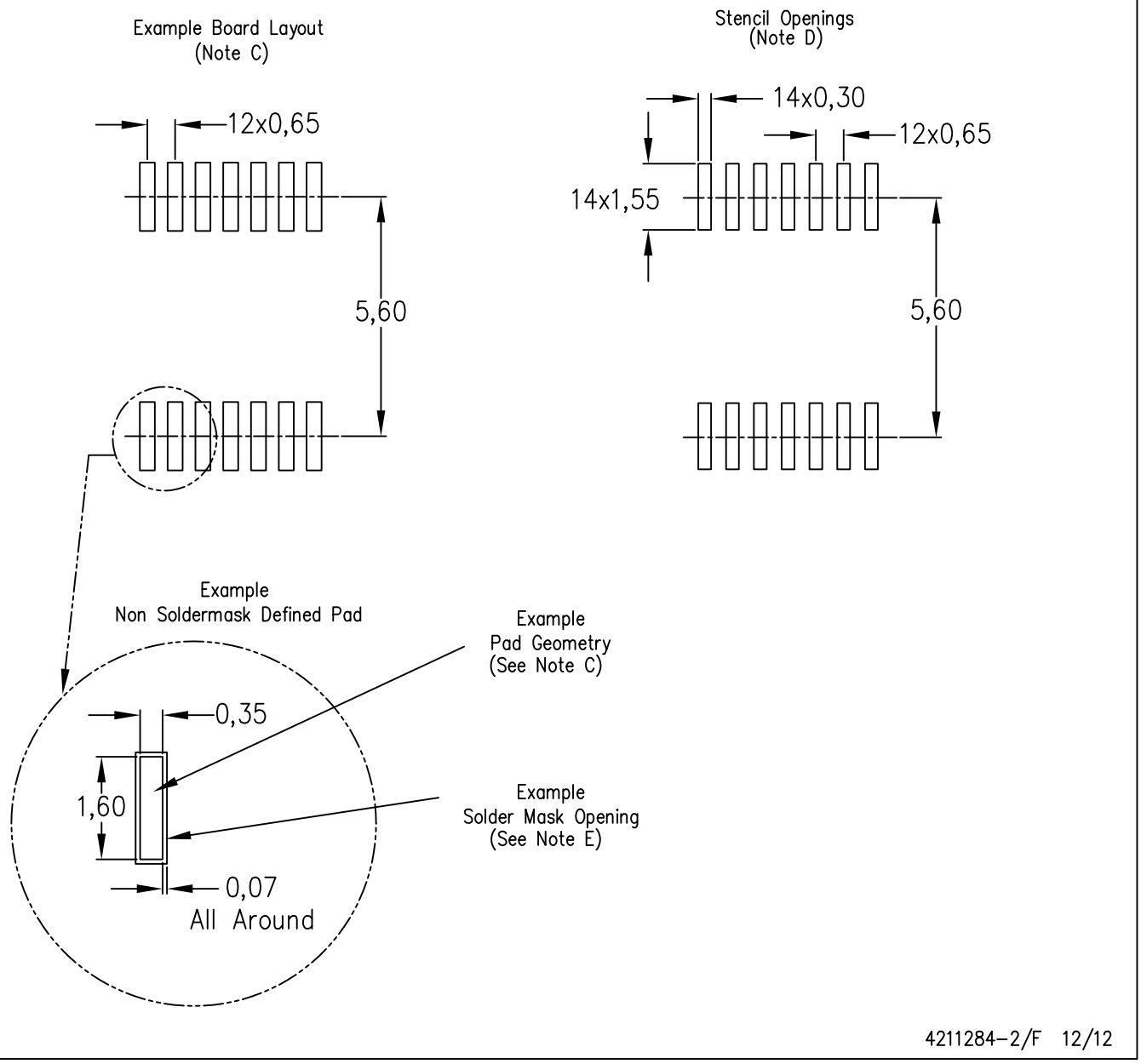
PW (R–PDSO–G14) PLASTIC SMALL OUTLINE




4040064–3/G 02/11

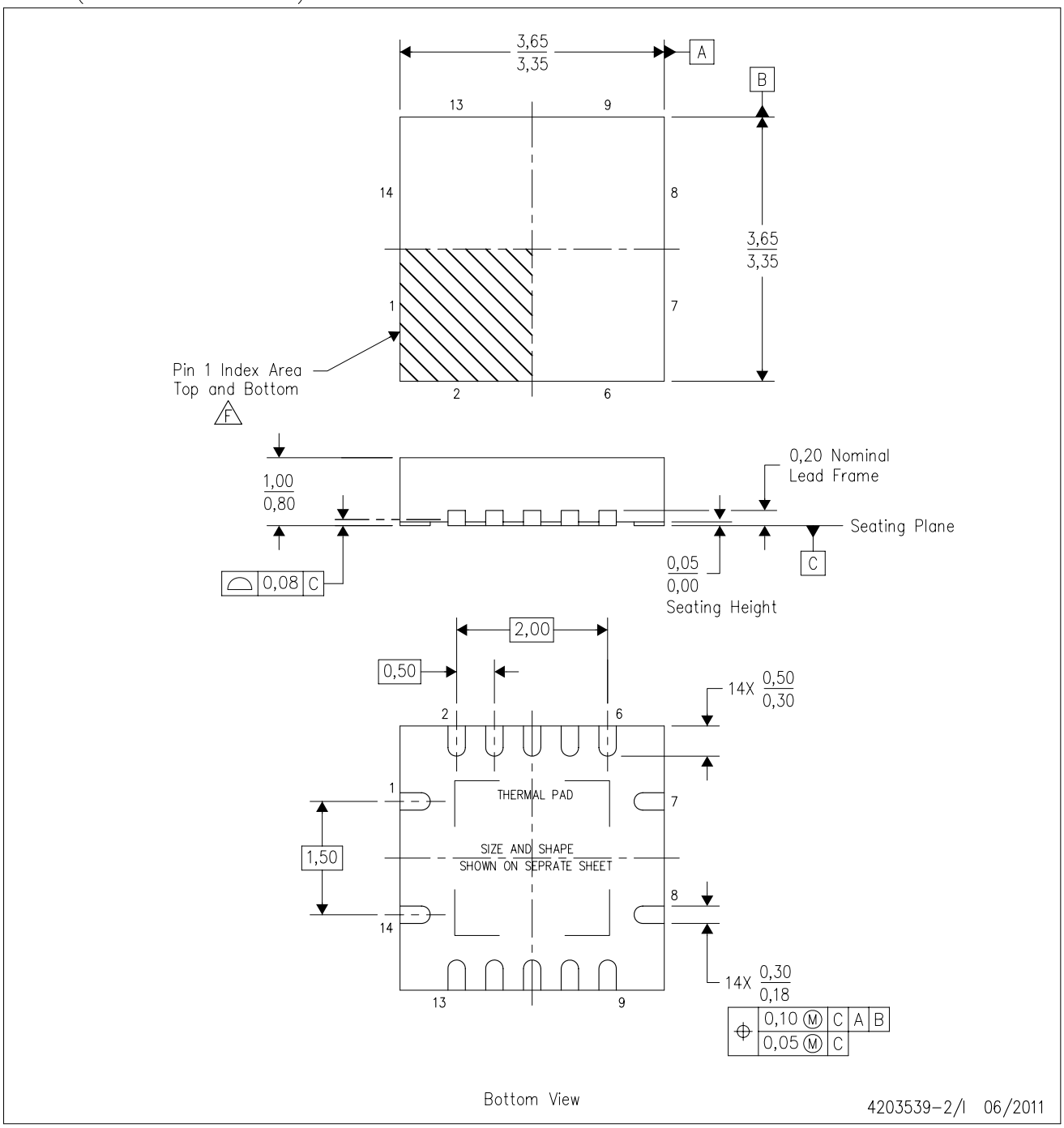
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G14) PLASTIC SMALL OUTLINE




NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RGY (S–PVQFN–N14) PLASTIC QUAD FLATPACK NO–LEAD




NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
G. Package complies to JEDEC MO–241 variation BA.

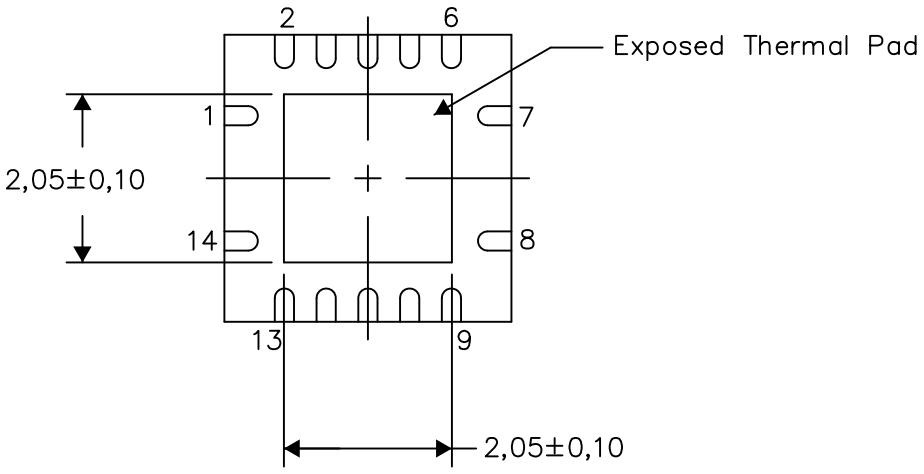
RGY (S–PVQFN–N14) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



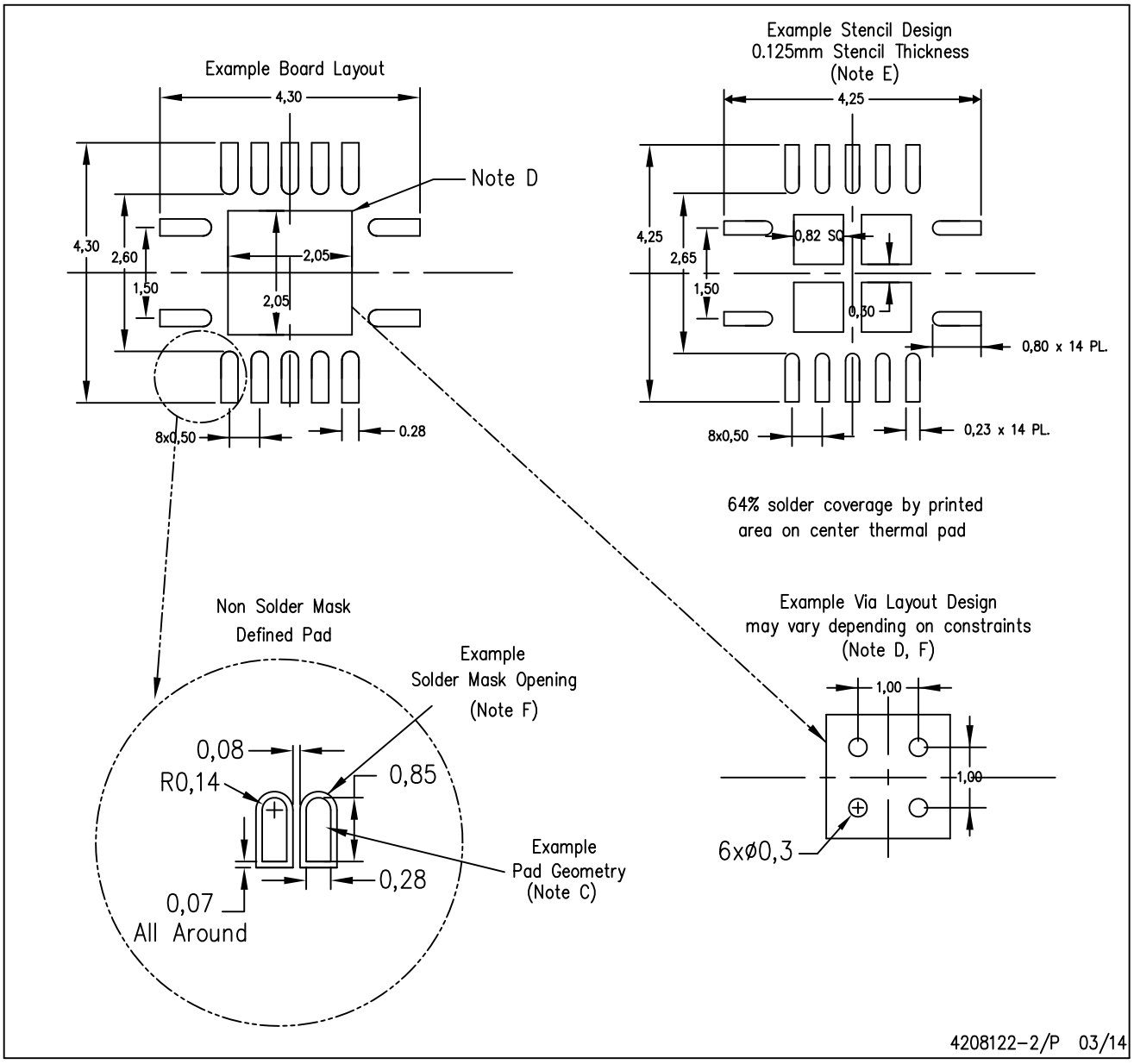

Bottom View

Exposed Thermal Pad Dimensions

4206353–2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S–PVQFN–N14) PLASTIC QUAD FLATPACK NO–LEAD

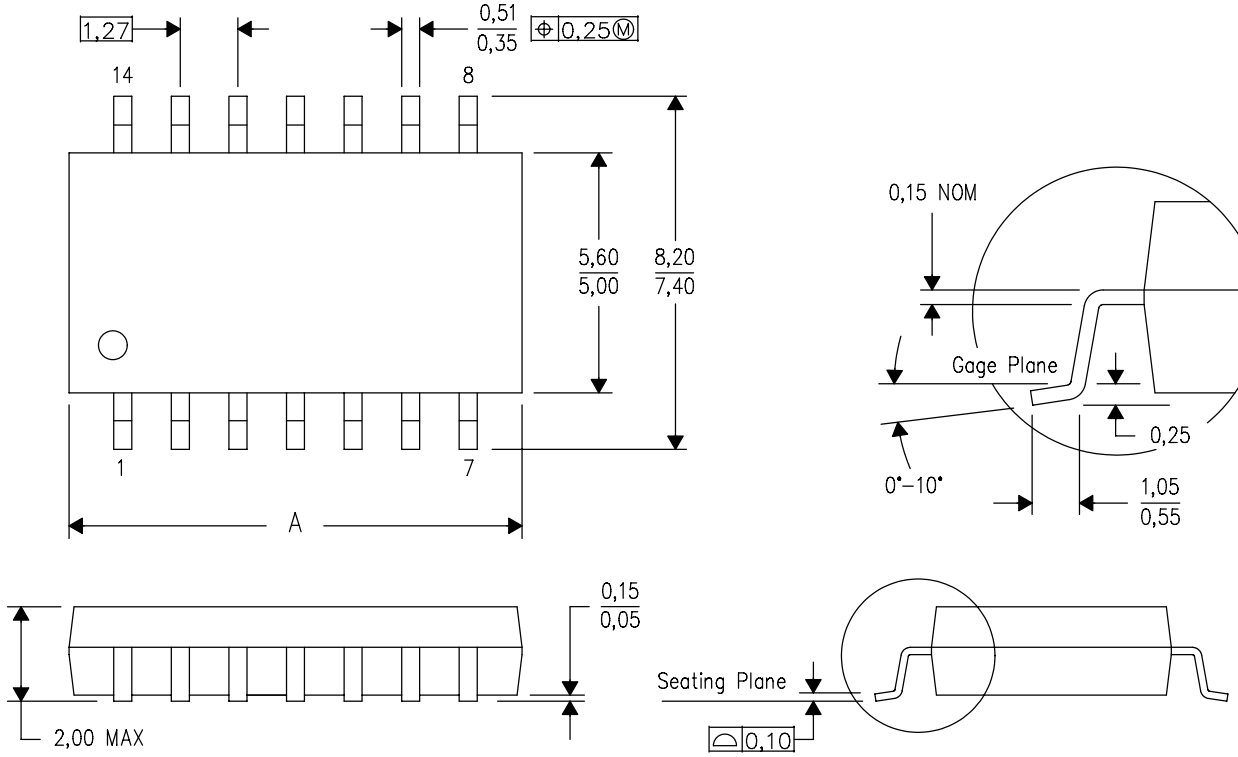



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http: //www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

## MECHANICAL DATA

**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

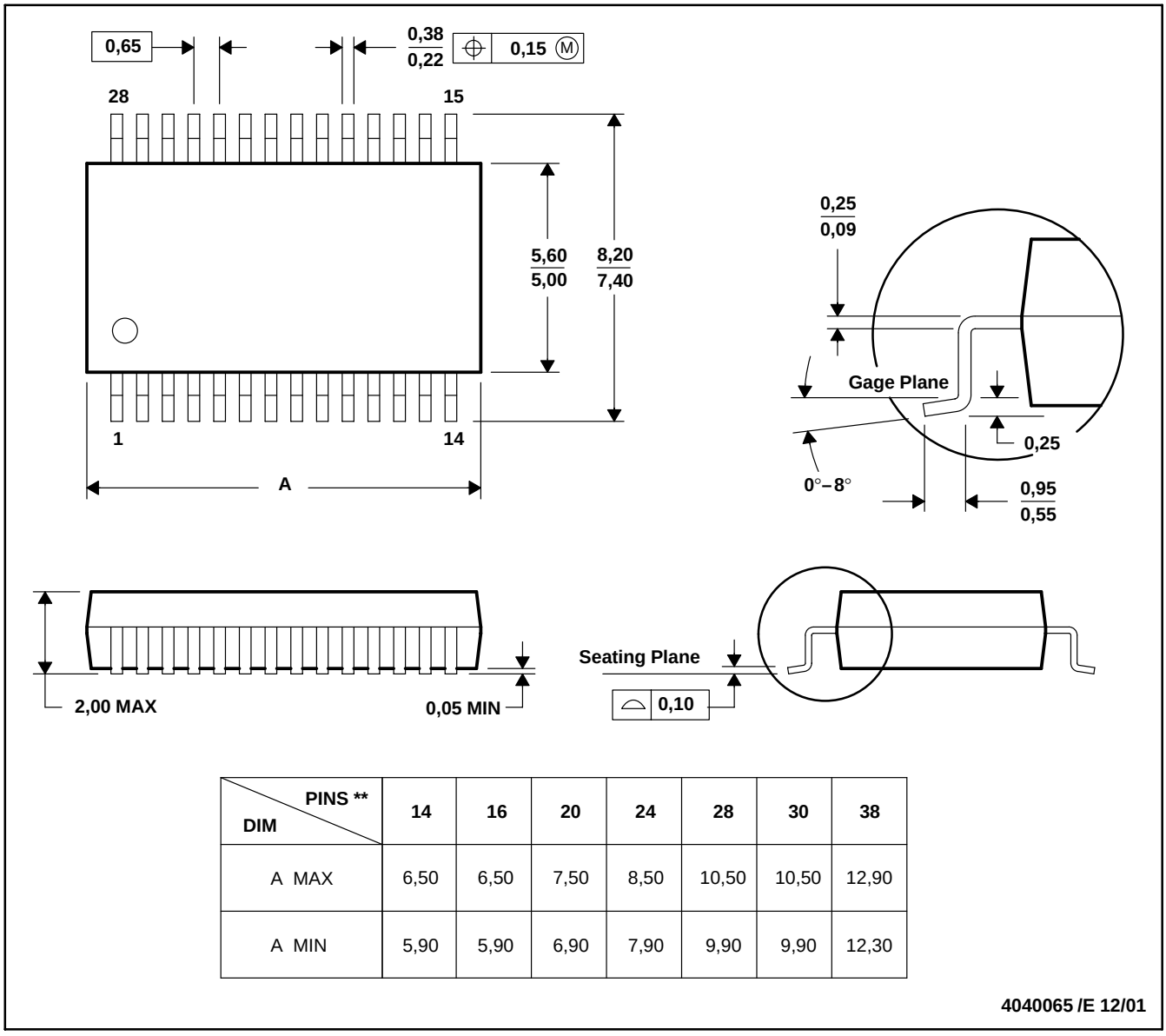
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

**DB (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE**

**28 PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 | 28 | 30 | 38 |
|---|---|---|---|---|---|---|---|
| A MAX | 6,50 | 6,50 | 7,50 | 8,50 | 10,50 | 10,50 | 12,90 |
| A MIN | 5,90 | 5,90 | 6,90 | 7,90 | 9,90 | 9,90 | 12,30 |

**4040065 /E 12/01**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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